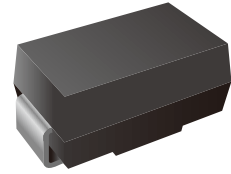
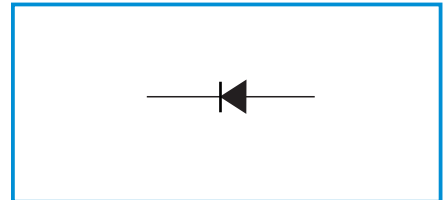


Surface Mount Ultra Fast Recovery Rectifier



Functional Diagram



Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives

Mechanical Data

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz
- Polarity: Color band denotes cathode end

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTU2A	LTU2B	LTU2D	LTU2G	LTU2J	LTU2K	LTU2M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$	$I_{F(AV)}$	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.0		1.3		1.65			V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100							μA
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50				75			ns
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	65 20							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings And Characteristics Curves

Fig.1 Forward Current Derating Curve

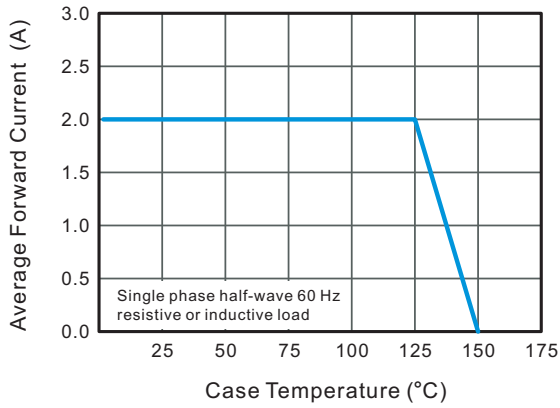


Fig.2 Typical Reverse Characteristics

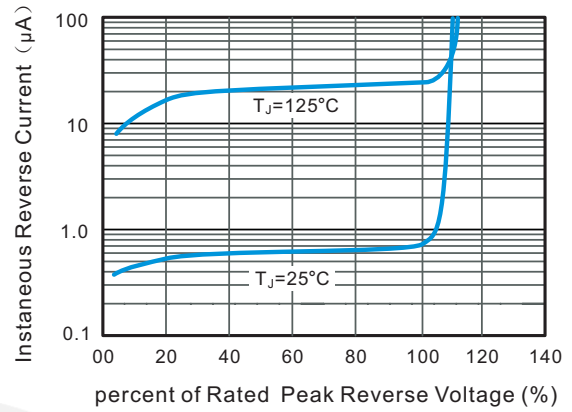


Fig.3 Typical Forward Characteristics

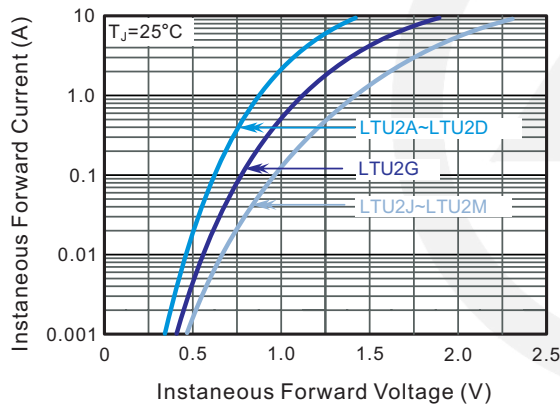
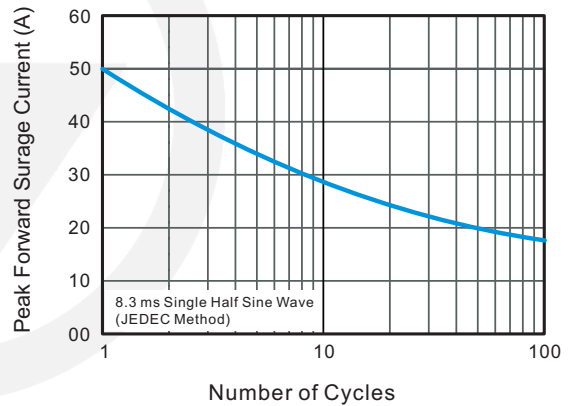
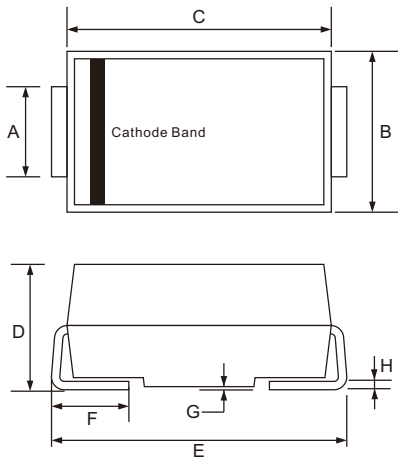


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current



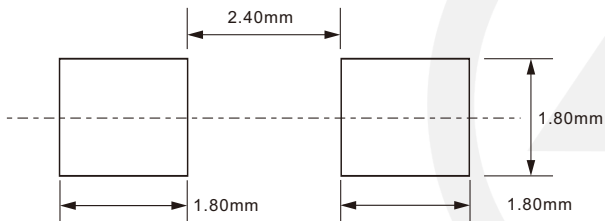
SMA Package Outline



Unit : mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.25	1.65
B	2.30	2.79
C	4.00	4.75
D	1.90	2.50
E	4.70	5.28
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

SMA Suggested Pad Layout

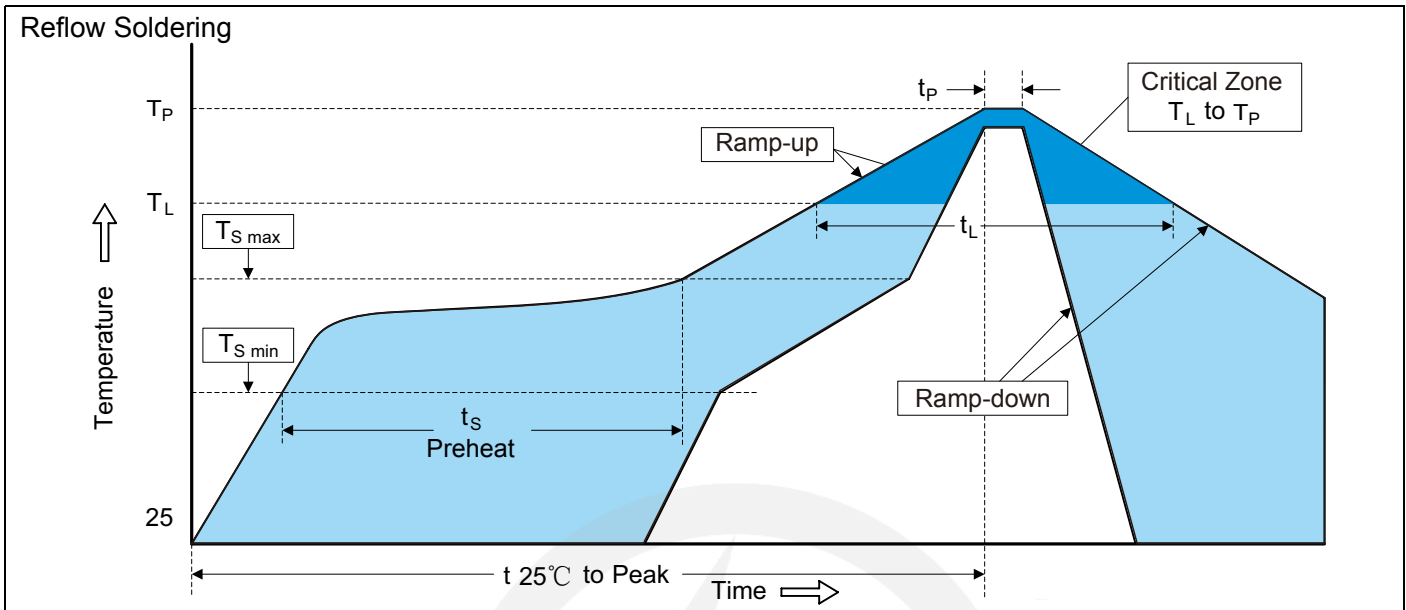


Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Marking

Type number	Marking code
LTU2A	U2A or US2A
LTU2B	U2B or US2B
LTU2D	U2D or US2D
LTU2G	U2G or US2G
LTU2J	U2J or US2J
LTU2K	U2K or US2K
LTU2M	U2M or US2M

Recommended Soldering Conditions

Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

13" Reel


 D5 $\Phi 330.0 \pm 2.0$

 D6 $\Phi 13.5 \pm 0.5$

 H 2.5 ± 1.0

 W2 16.0 ± 2.0

Quantity: 5000PCS